

Karbon 700-SE-2

High-Performance Rugged Computing, Evolved

Karbon 700-SE-2 brings power, reliability, and connectivity to the edge.

onlogic.com/k700-se-2



Built To Do More

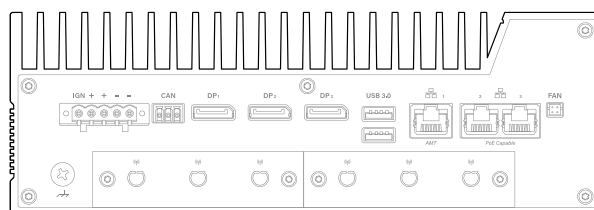
Karbon 700-SE-2 reaches a new peak of rugged computing with powerful 8-core i7 or Xeon processing.

Designed For The Edge

Deployment is easy with Karbon 700-SE-2, with deeply customizable DIO, integrated CAN bus, automotive power and flexible I/O configurations via ModBay™ expansion.

Engineered To Last

Rugged fanless design, wide operating temperature range, and leading shock and vibration resistance give Karbon 700-SE-2 the durability for the toughest computing environments.



US Office

Phone: +1 802 861 2300 | Email: info@onlogic.com | www.onlogic.com

EU Office

Phone: +31 088 5200 700 | Email: info@onlogic.eu | www.onlogic.com

System	
Processor	Support for Intel 8th & 9th Gen Processors Xeon E-2124G, E-2176G, E-2226GE, E-2278GE, E-2278GEL Core i7-8700, i7-8700T, i7-9700E, i7-9700TE Core i5-8500, i5-8500T, i5-9500E, i5-9500TE Core i3-8100, i3-8100T, i3-9100E, i3-9100TE Pentium 5400, 5400T Celeron 4900, 4900T
Processor Speed	1.8 ~ 3.7 GHz
Processor Cores	2 ~ 8
Chipset	Intel C246
Integrated Graphics	Intel UHD Graphics 610/630
Memory	2 DDR4 SO-DIMM slots 4 ~ 64 GB (ECC or non-ECC)

Rear I/O	
Ethernet	1 GbE LAN with Intel I219-LM controller 2 GbE LAN with Intel I210-AT controllers (PoE optional)
USB	2 USB 3.1 Gen 1
Video	3 DisplayPort
Power	5-Pin Terminal Block Power Input (9-36V) Intelligent Ignition Sensing
Other	3-pin CAN bus 2 ModBay (4 LAN, 4 PoE, etc.) External Fan Connection

Front I/O	
USB	4 USB 3.1 Gen 1
Serial	2 RS-232/422/485 COM
Other	8-bit Isolated Digital I/O (4-in, 4-out) 2-pin Remote Power Switch 2 2.5" Hot-Swap Drives (optional) External Mini-SIM slot Power button

Expansion & Features	
Expansion & Storage	1 M.2 2280 M-key (PCIe x4, SATA) 1 M.2 2230/60/80 M-key (PCIe x2) 1 M.2 2230 E-key 1 mPCIe = PCIe x1 and USB 2.0. 1 mPCIe = USB 2.0 and SMBUS (For the SIM card) 2 2.5" SATA SSD/HDD drives 0-20mm max (hot-swap optional, 0-15mm max) Dual-slot PCIe expansion (1 PCIe x16 or 2 PCIe x8)
Onboard Connectors	2 ModBay for I/O Expansion
Features	Onboard TPM 2.0

Mechanical	
Dimensions (WxHxD)	240 x 143 x 242 mm (9.45 x 5.63 x 9.53 in)
Mounting Options	Wall-mount Wall-mount with Vibration Isolation

Environmental & Regulatory	
Operating Temperature	-40°C ~ 70°C with 35W TDP Processor -40°C ~ 50°C with 65W TDP Processor -40°C ~ 40°C with 80W TDP Processor
Storage Temperature	-40°C ~ 85°C
Shock	Tested according to IEC 60068-2-27 and MIL-STD-810G
Vibration	Tested according to IEC 60068-2-64 and MIL-STD-810G
Certifications	FCC 47 CFR Part 15 Low-Voltage (2014/35/EU) Electromagnetic Compatibility (2014/30/EU) Radio Equipment (2014/53/EU) - Only applicable for configurations with wireless transmitters EN 55032 EN 55035 RoHS 3 (2015/863/EU) WEEE Directive (2012/19/EU) Power Immunity According to E-Mark 7637-2 & 16750-2 EN 50121 Additional Safety and EMC certifications pending. Some certifications configuration dependent.

US Office

Phone: +1 802 861 2300 | Email: info@onlogic.com | www.onlogic.com

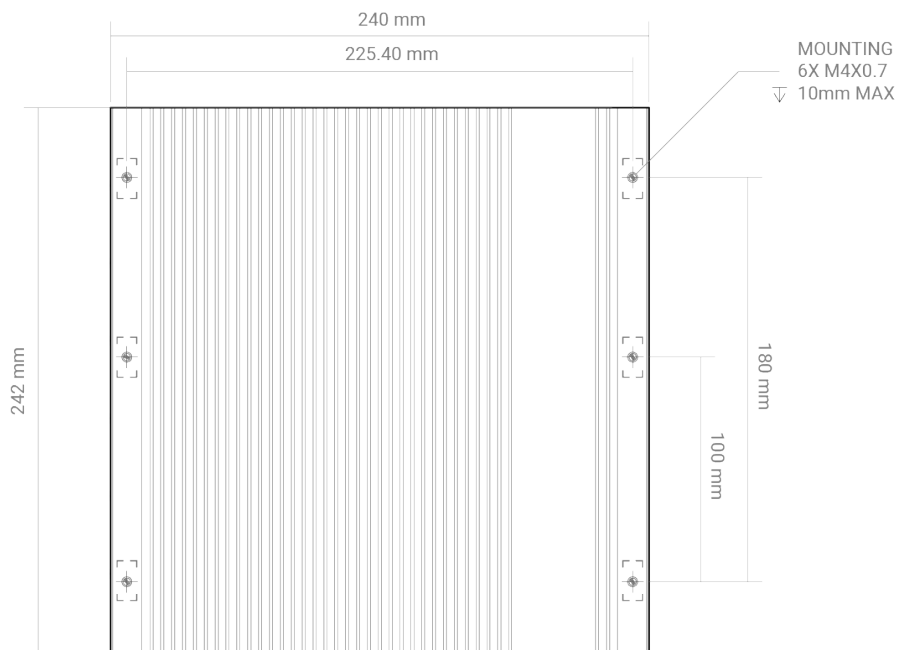
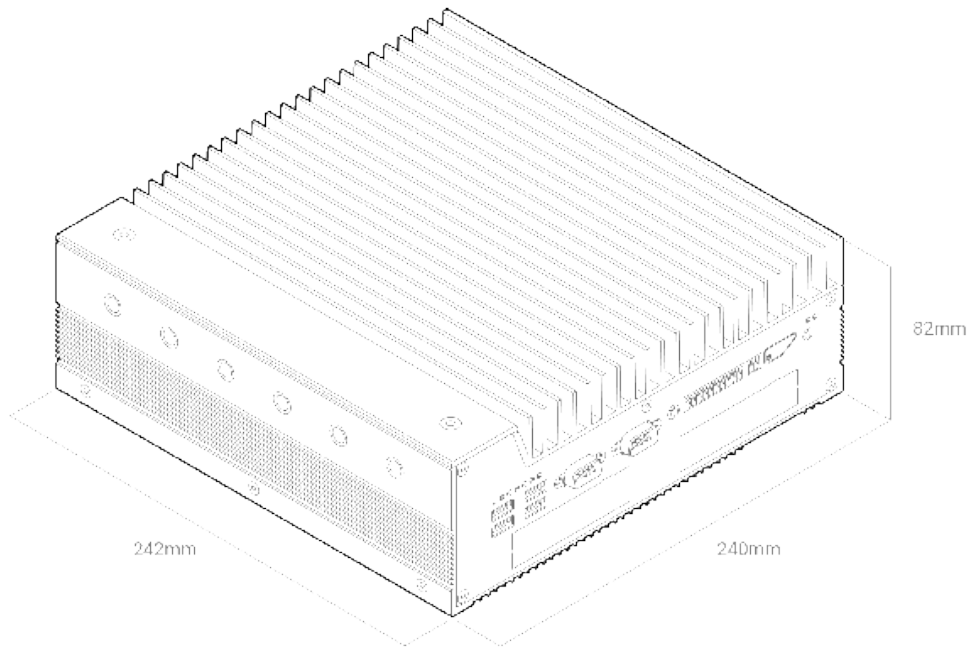
EU Office

Phone: +31 088 5200 700 | Email: info@onlogic.eu | www.onlogic.com

Karbon 700-SE-2 Dimensional Drawings

High-Performance Rugged Computing, Evolved

All measurements in mm



US Office

Phone: +1 802 861 2300 | Email: info@onlogic.com | www.onlogic.com

EU Office

Phone: +31 088 5200 700 | Email: info@onlogic.eu | www.onlogic.com